

# Printing Plate Punching System

**Status:** Available

**Group Members:** TBD

**Sponsor(s):** Kodak Graphic Communications Company Canada

**Supervisor(s):** Bob Dalton, PEng, Kodak Graphic Communications Company Canada  
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## Project Description

[Kodak](#) is a global leader in the design and manufacturing of laser based imaging systems that leverage precision opto-mechanical systems to achieve high levels of accuracy. We would like to add a feature known as plate punching to one of our product lines. The project would involve taking an existing punch module, already developed by Kodak, which includes a plate conveying system, registration system and punching system and incorporating it into an existing imaging system including all of the associated mechanical, electrical and firmware components. All equipment and lab space are available to the students in our facility in Burnaby.